

PCN Number:	20181022004.0	PCN Date:	October 24, 2018
Title:	Datasheet for TMP303		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



TMP303

SBOS486H – JULY 2009 – REVISED OCTOBER 2018

Changes from Revision G (July 2017) to Revision H	Page
• Changed supply voltage maximum value in the <i>Absolute Maximum Ratings</i> table from: 3.6 V to: 4 V	5
• Changed input pin voltage maximum value in the <i>Absolute Maximum Ratings</i> table from: $V_S + 0.5$ V to: $((V+) + 0.5)$ and ≤ 4	5
• Changed output pin voltage maximum value in the <i>Absolute Maximum Ratings</i> table from: $V_S + 0.5$ V to: $((V+) + 0.5)$ and ≤ 4	5
• Updated junction-to-ambient thermal resistance from 168 °C/W to 210.3 °C/W	5
• Updated junction-to-case (top) thermal resistance from 2.4 °C/W to 105.0 °C/W	5
• Updated junction-to-board thermal resistance from 42.3 °C/W to 87.5 °C/W	5
• Updated junction-to-top characterization parameter from 0.9 °C/W to 6.1 °C/W	5
• Updated junction-to-board characterization parameter from 42.3 °C/W to 87.0 °C/W	5

The datasheet number will be changing.

Device Family	Change From:	Change To:
TMP303	SBOS486G	SBOS486H

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/TMP303>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

TMP303ADRLR	TMP303ADRLT	TMP303BDRLR	TMP303DDRLT
TMP303CDRLR	TMP303CDRLT	TMP303DDRLR	TMP303FDRLT
TMP303EDRLR	TMP303EDRLT	TMP303FDRLR	
TMP303GDRLR	TMP303GDRLT	TMP303BDRLT	

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com